Materials Declaration

Package	Sidebraze
Body Size	600 mils
Lead Count	24
Option	Au

Combolid

Item	% of Combolid	Weight (g)	PPM
Kovar	92	3.05E-01	183645
Nickel	4	1.32E-02	7985
Gold	4	1.32E-02	7985
Subtotal		3.31E-01	199614

Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	2.23 E-02	13438
Sn	20.42	5.72 E-03	3448
Subtotal		2.80 E-02	16886

Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Ceramic			
Al2O3	90.5	8.51 E-01	513026
Cr2O3	3.9	3.67 E-02	22108
SiO2	3.5	3.29 E-02	19841
TiO2	1.0	9.40 E-03	5669
Cao	0.6	5.64 E-03	3401
MgO	0.5	4.70 E-03	2834
Subtotal		9.40 E-01	566880
Metallization			
Tungsten	96.61	4.83 E-02	29131
Molybdenum	3.39	1.70 E-03	1022
Subtotal		5.00 E-02	30153
Lead			
Iron	58	1.51 E-01	90942
Nickel	40.7	1.06 E-01	63816
Manganese	0.8	2.08 E-03	1254
Cobalt	0.5	1.30 E-03	784
Subtotal		2.60 E-01	156797
Ag-Cu (base metal)			
Silver	85	8.50 E-03	5126
Copper	15	1.50 E-03	905
Subtotal		1.00 E-02	6031
Nickel Plating (1st coating)			
Nickel	93.89	9.39 E-03	5662
Palladium	5.36	5.36 E-04	323
Boron	0.7	7.00 E-05	42
Lead	0.05	5.00 E-06	3
Subtotal		1.00 E-02	6031
Nickel Plating (2nd layer)			
Nickel	92	9.20 E-03	5548
Cobalt	8	8.00 E-04	482
Subtotal		1.00 E-02	6031

External Leadframe Plating

Item	% of External Plating	Weight (g)	PPM
Gold	100	1.00 E-02	6031

Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.30 E-03	784

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	4041

Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	579
Cyanate ester resin	20	2.40 E-04	145
		1.20 E-03	724

Package Totals

Weight (g)	PPM
1.66E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Materials Declaration

Package	Sidebraze
Body Size	600 mils
Lead Count	24
Option	SnPb

Combolid

Item	% of Combolid	Weight (g)	PPM
Kovar	92	3.05E-01	125986
Nickel	4	1.32E-02	5478
Gold	4	1.32E-02	5478
Subtotal		3.31E-01	136941

Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	2.23 E-02	9219
Sn	20.42	5.72 E-03	2365
Subtotal		2.80 E-02	11584

Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Al2O3	77.97	1.57 E+00	651605
Iron	6.31	1.27 E-01	52733
Nickel	4.86	9.82 E-02	40616
Chromium	3.60	7.27 E-02	30086
SiO2	3.20	6.46 E-02	26743
Tungsten	2.00	4.04 E-02	16714
CaO	0.60	1.21 E-02	5014
MgO	0.50	1.01 E-02	4179
Ag	0.50	1.01 E-02	4179
Co	0.20	4.04 E-03	1671
Gold	0.16	3.23 E-03	1337
Cu	0.10	2.02 E-03	836
Subtotal		2.02 E+00	835712

Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.20 E-03	496

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	2772

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	63	1.83 E-02	7559
Pb	37	1.07 E-02	4439
Subtotal		2.90 E-02	11998

Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	397
Cyanate ester resin	20	2.40 E-04	99
Subtotal		1.20 E-03	496

Package Totals

Weight (g)	PPM
2.42E+00	1000000

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